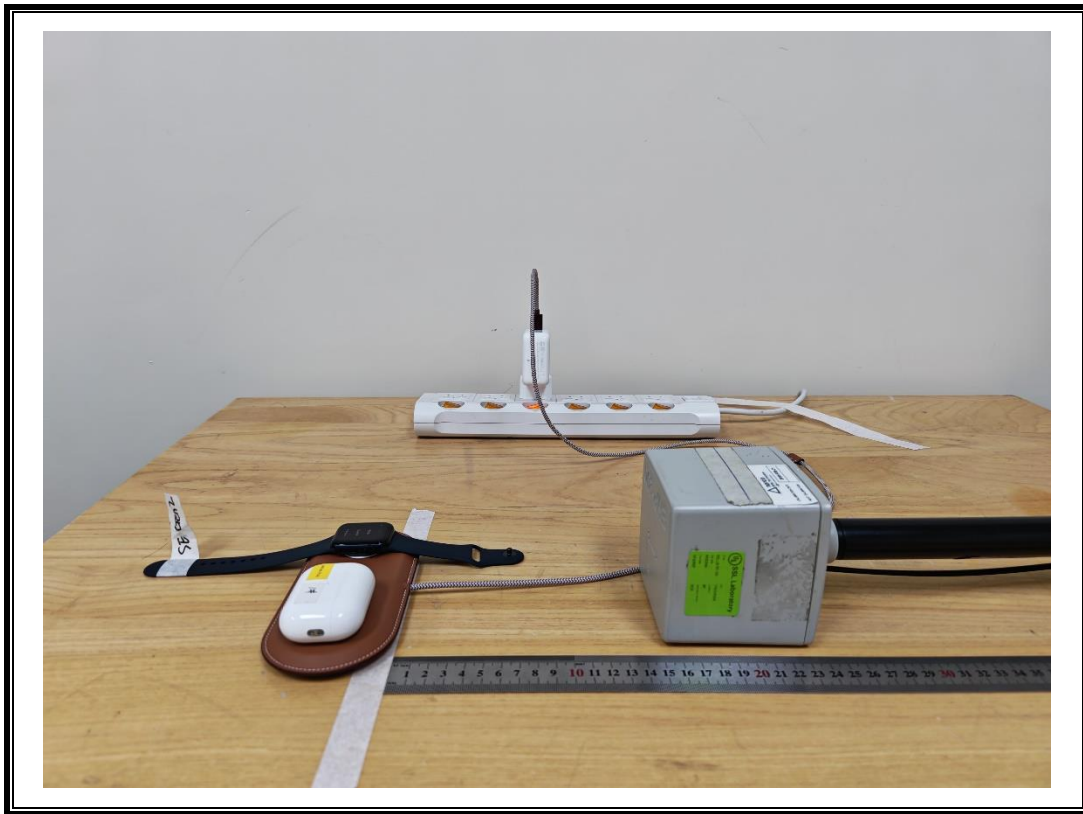


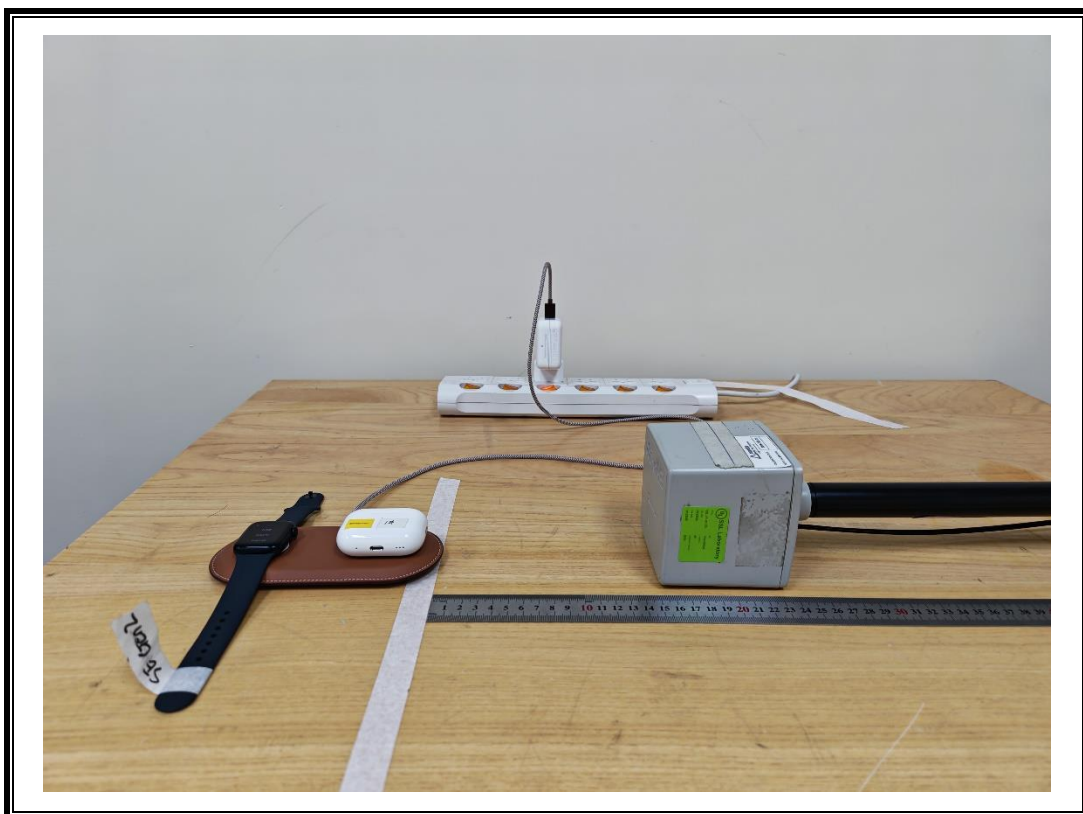
Appendix III -1

Setup Photographs

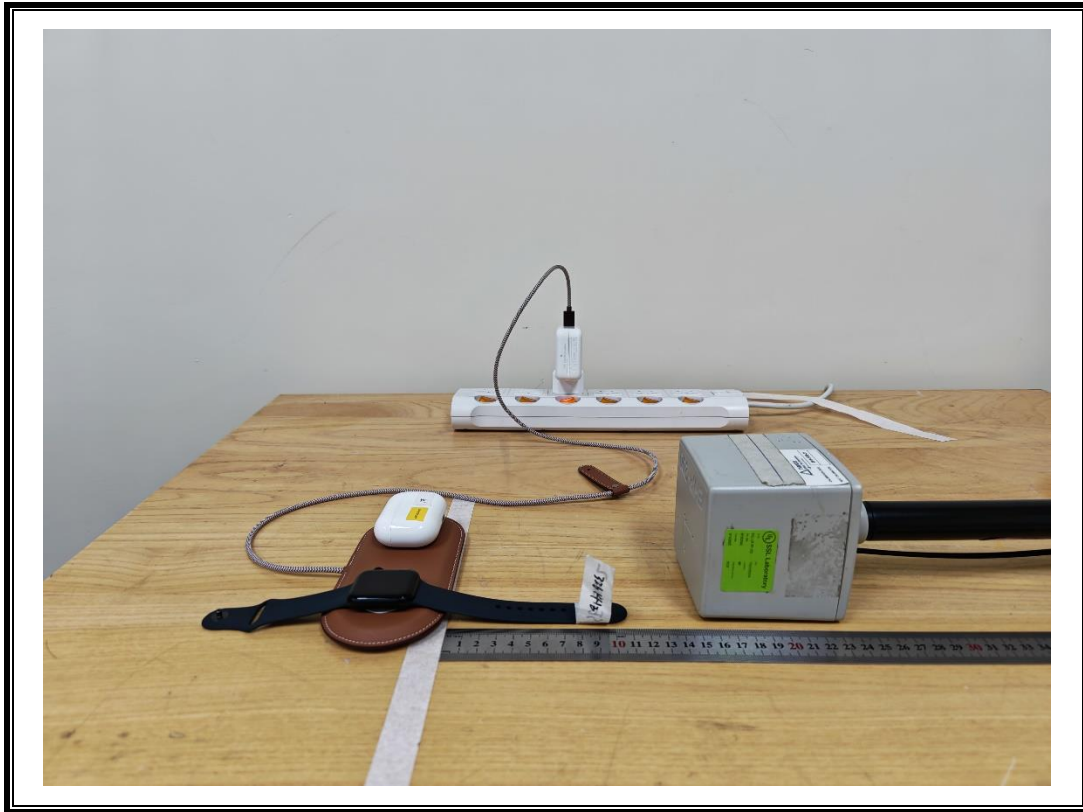
E-FILED AND H-FILED STRENGTH MEASUREMENT SETUP-1



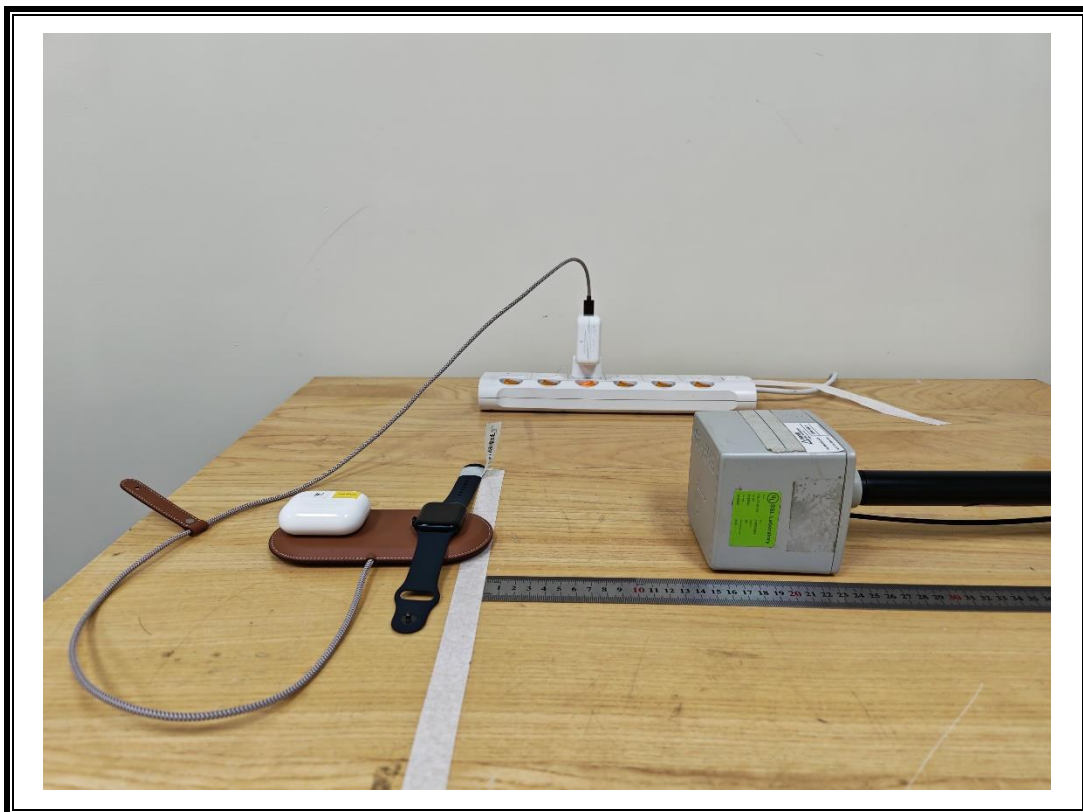
E-FILED AND H-FILED STRENGTH MEASUREMENT SETUP-2



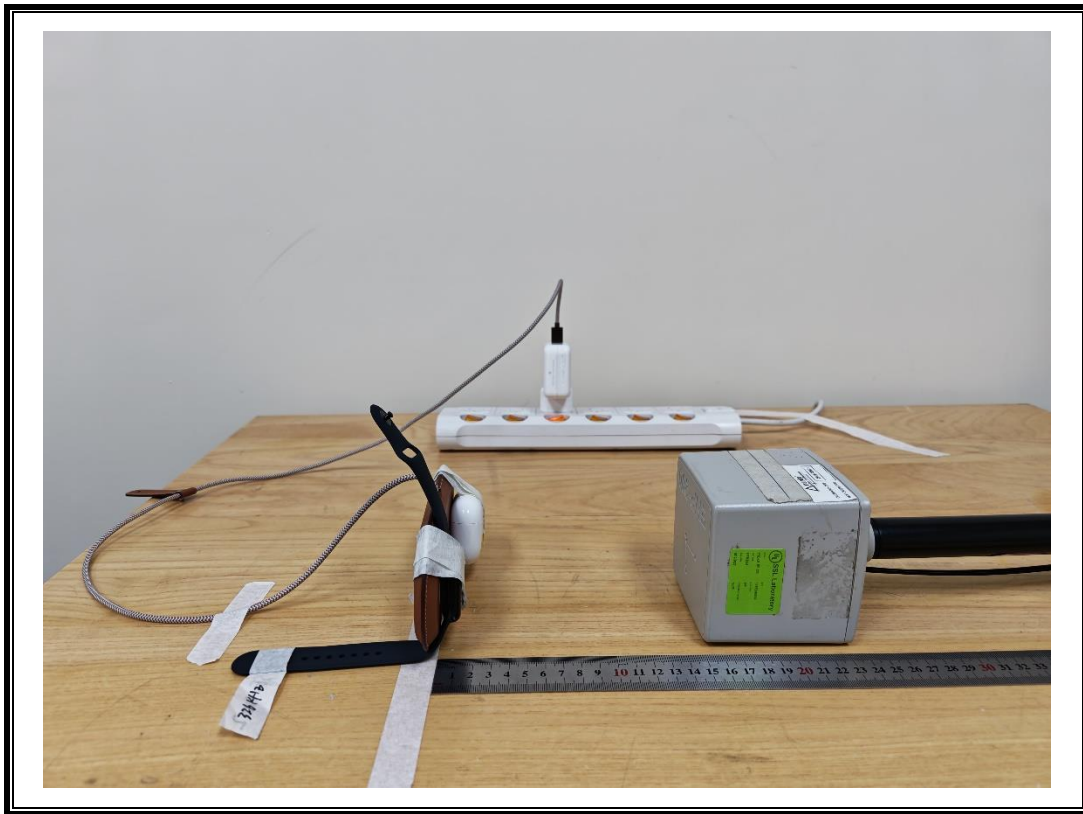
E-FILED AND H-FILED STRENGTH MEASUREMENT SETUP-3



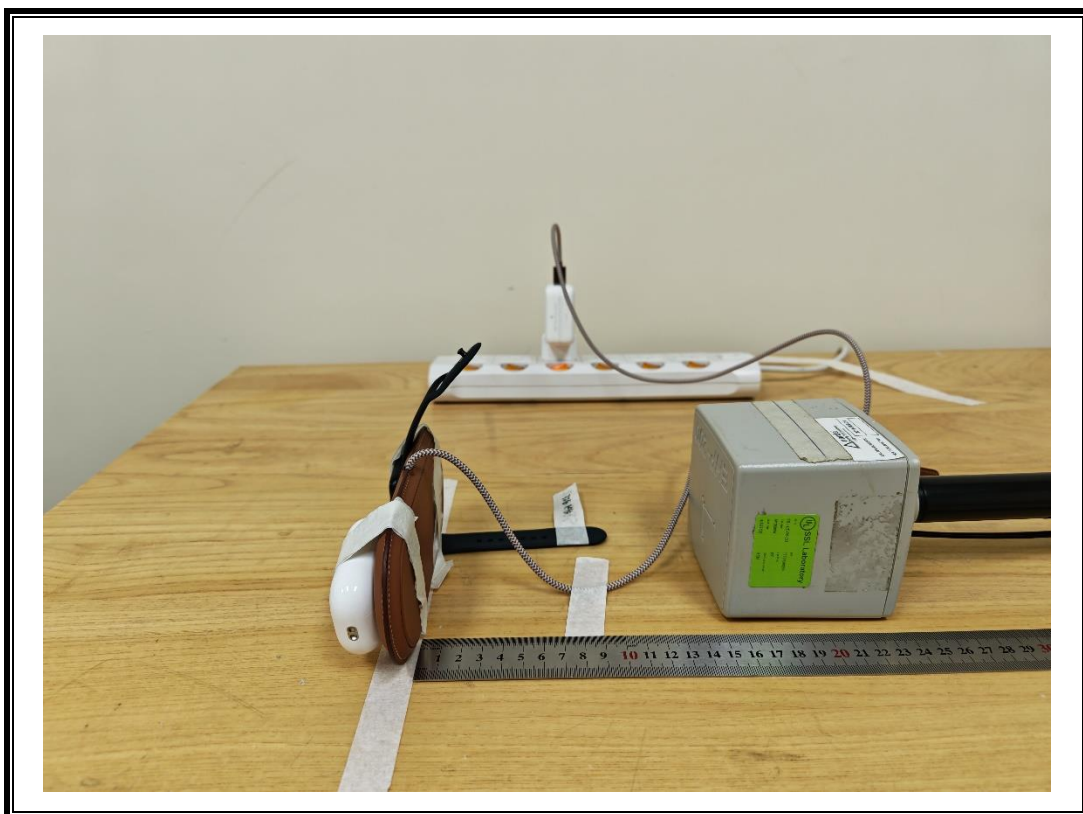
E-FILED AND H-FILED STRENGTH MEASUREMENT SETUP-4



E-FILED AND H-FILED STRENGTH MEASUREMENT SETUP-5

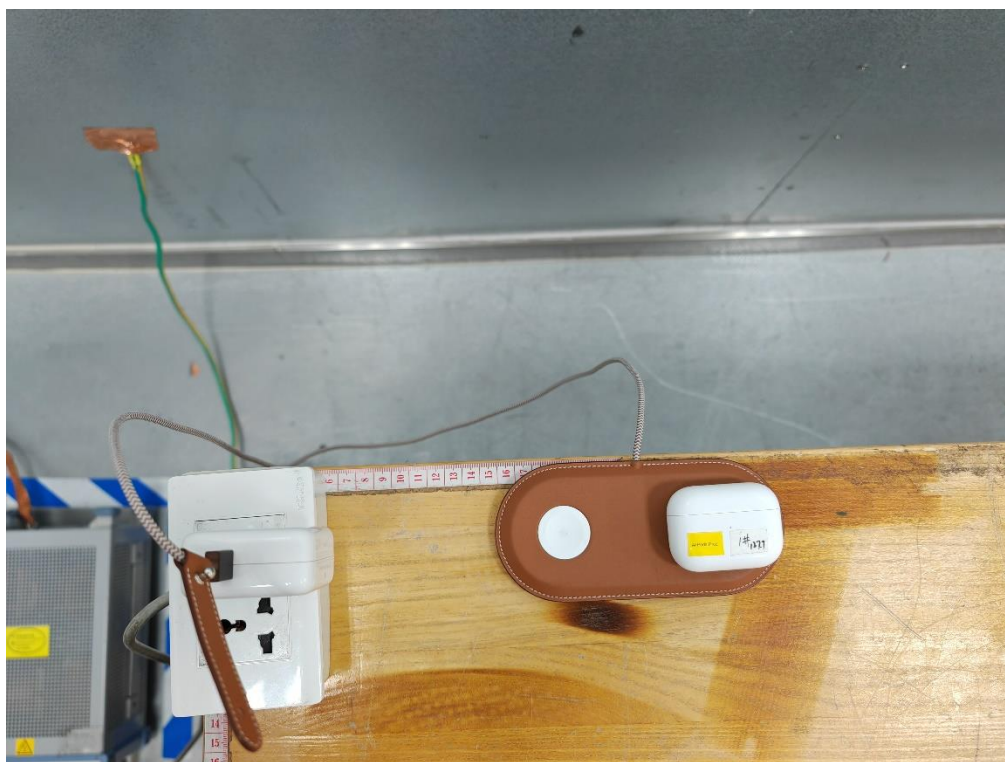
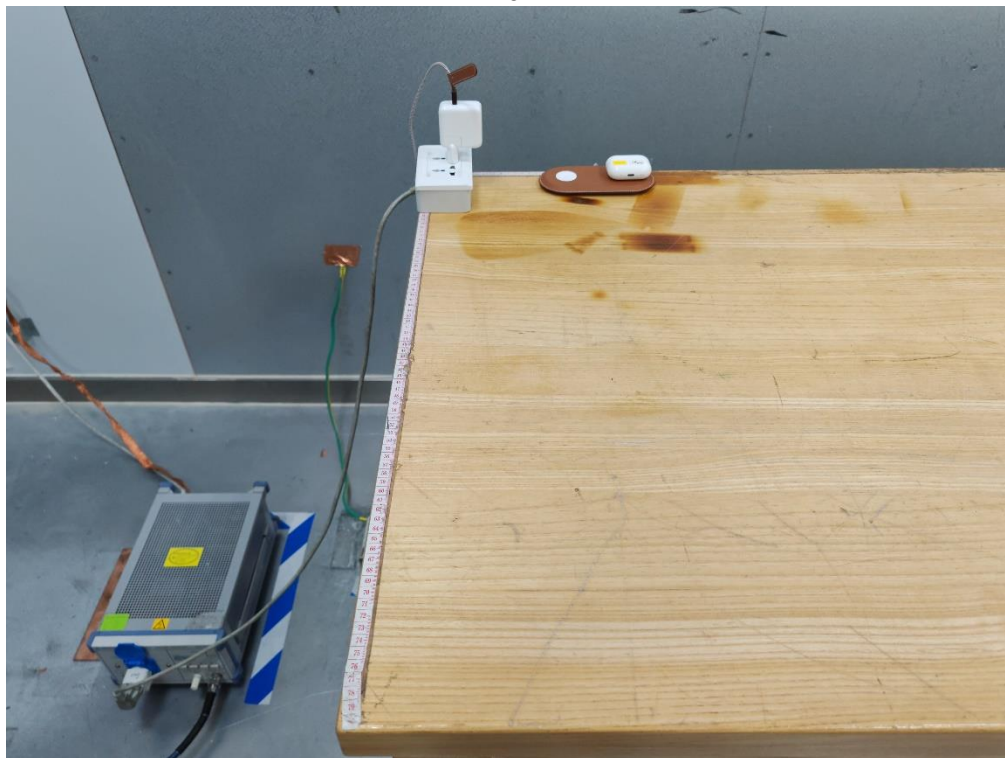


E-FILED AND H-FILED STRENGTH MEASUREMENT SETUP-6

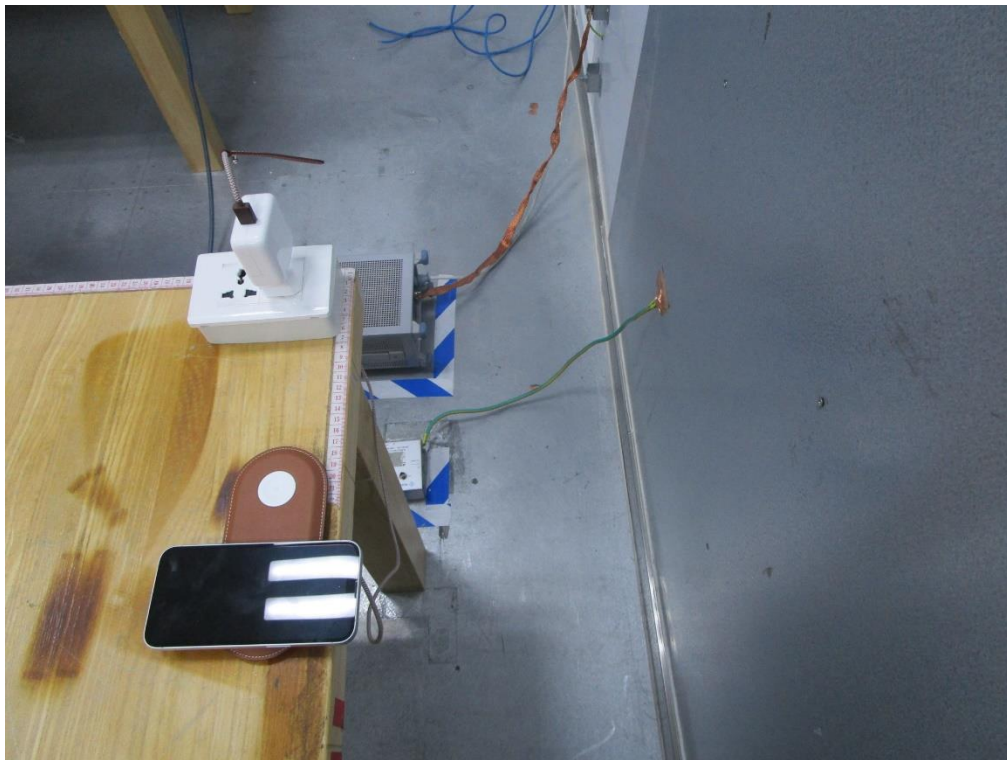
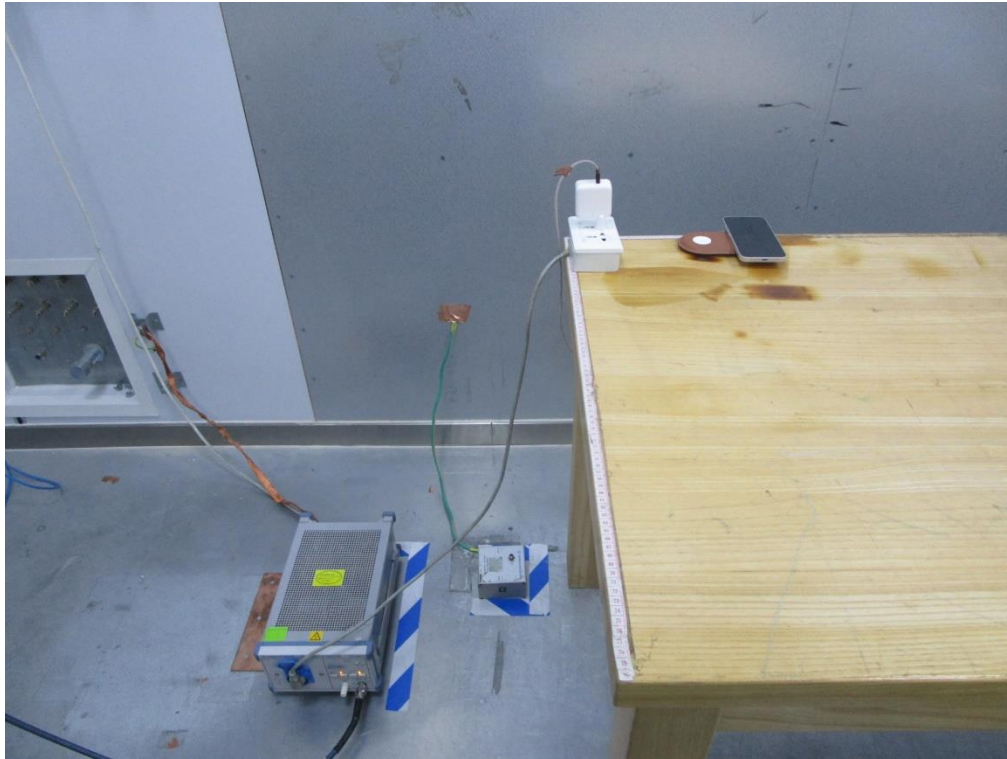


Conducted emissions

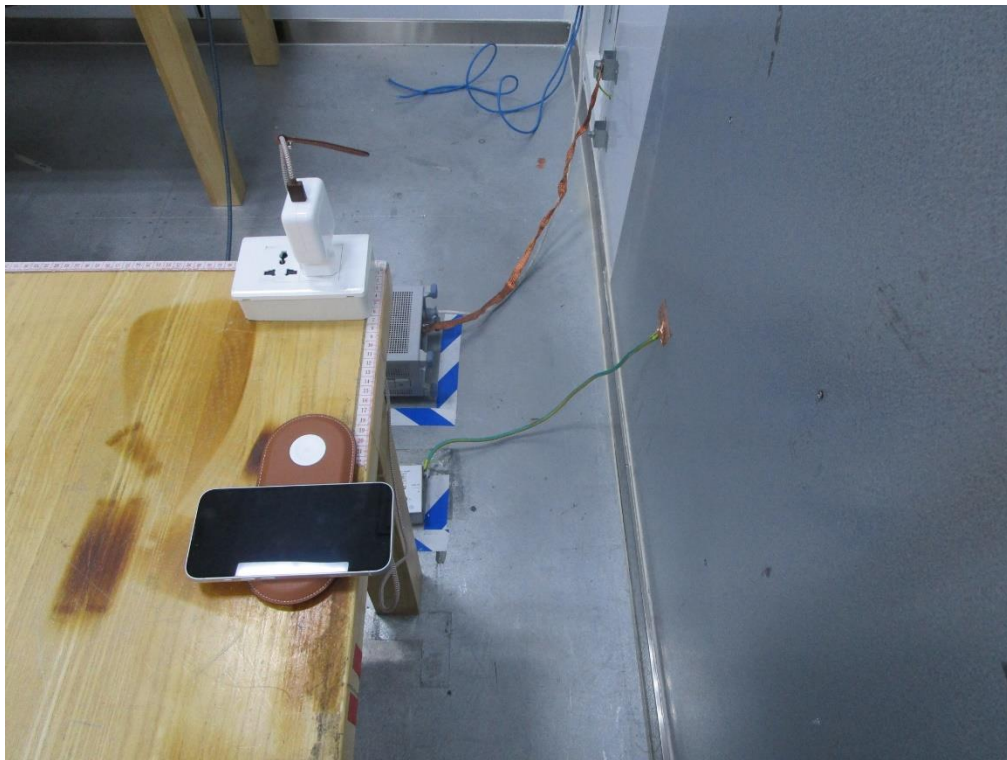
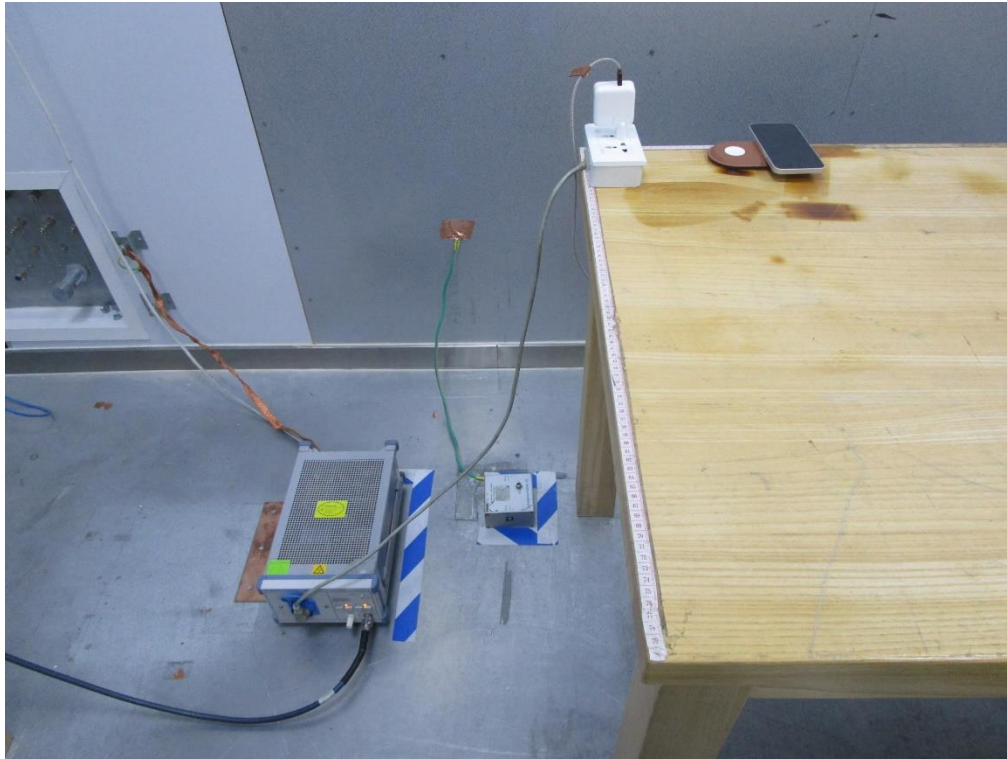
M01



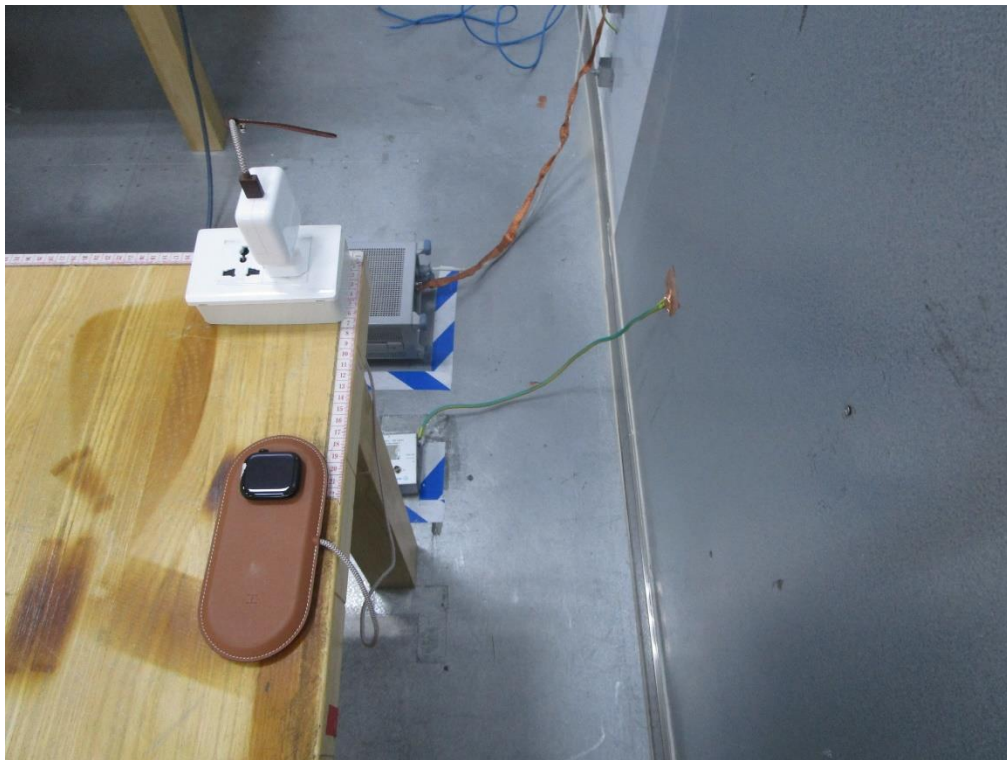
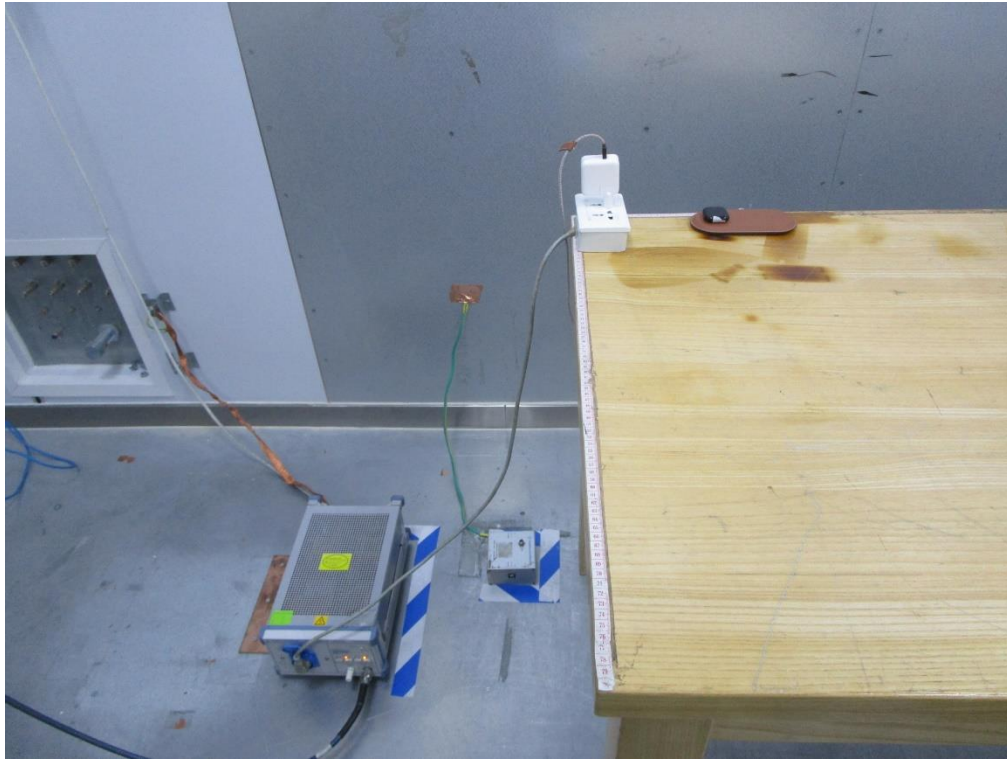
M02



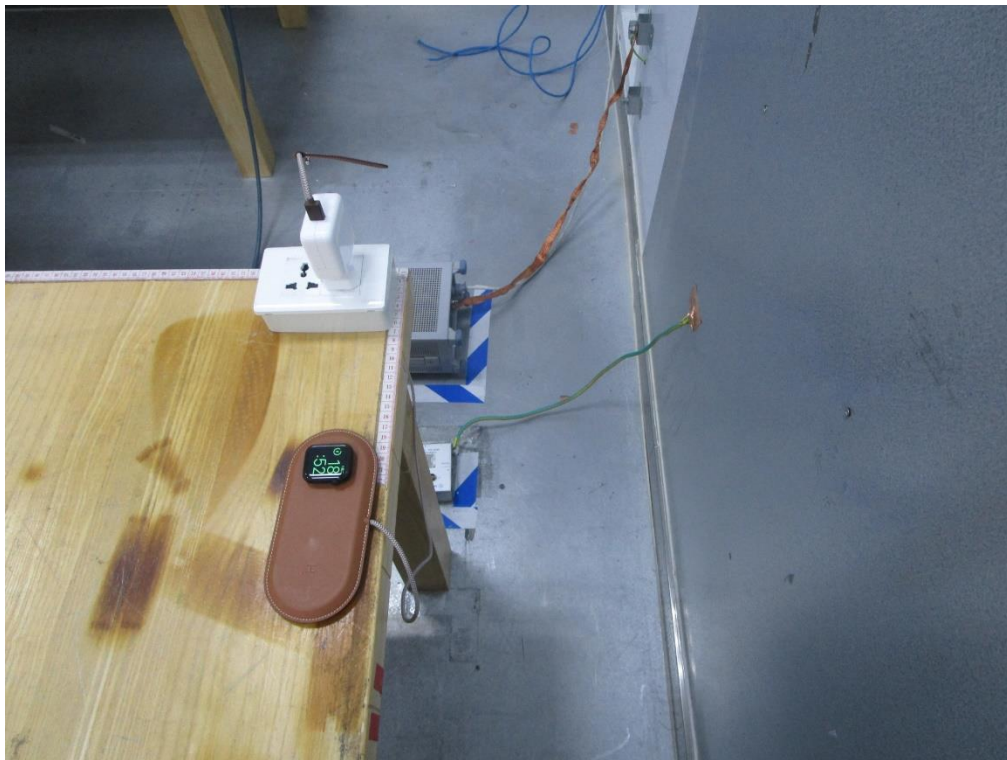
M03



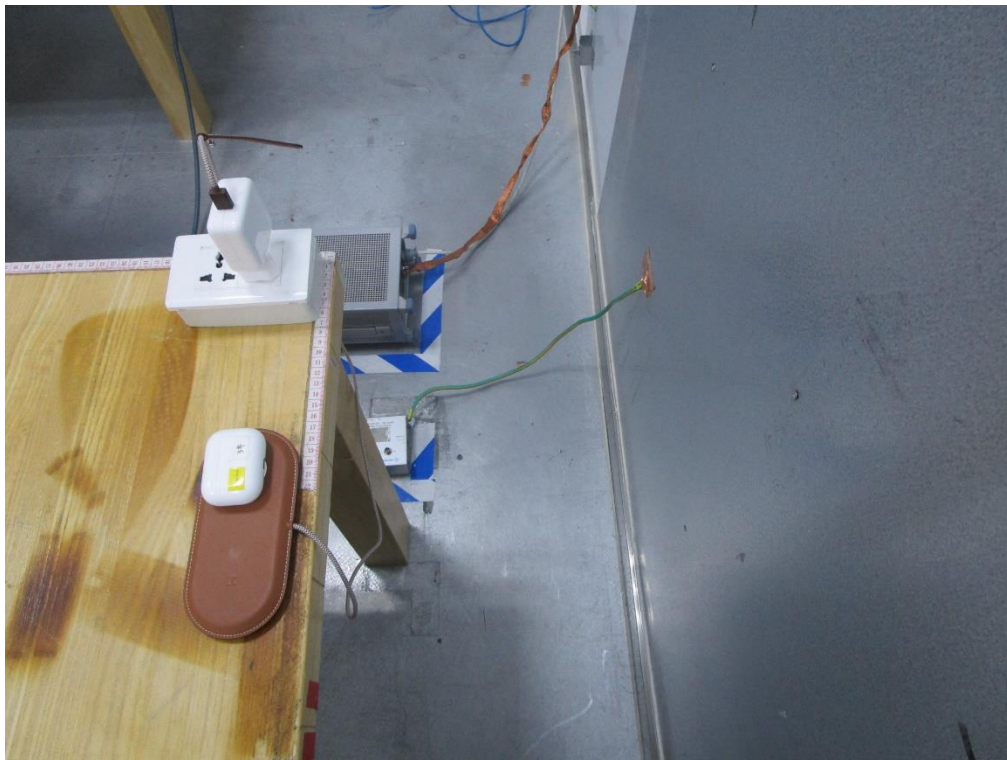
M04



M05



M06



Radiated emissions below 30MHz

M01



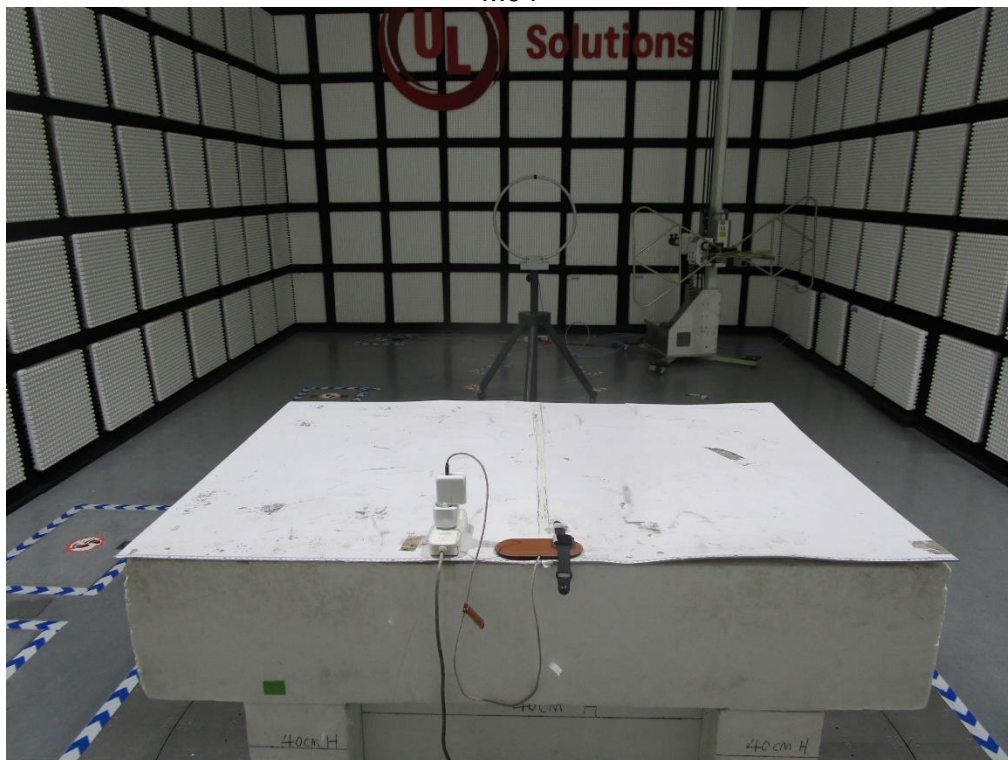
M02



M03



M04



M05



M06



Radiated emissions below 1GHz

M01



M02



M03



M04



M05



M06

